# Abstracts

## An L-Band Power Amplifier Multi-Chip-Module Using Multi-Layered Planar Circuits

*M. Ida, H. Suzaki, T. Yamanaka and T. Nishikawa. "An L-Band Power Amplifier Multi-Chip-Module Using Multi-Layered Planar Circuits." 1994 MTT-S International Microwave Symposium Digest 94.3 (1994 Vol. III [MWSYM]): 1649-1652.*

A power amplifier Multi-Chip-Module (MCM) was developed for an L-band digital cordless telephone. To realize both the high power added efficiency and small outline, MMIC design in the MCM is combined with design of a multi-layered planar circuit. The maximum gain of 37.1 dB and output power of 25.6 dBm are obtained at 1.9 GHz. Maximum total power added efficiency is 25% at 2.0 GHz. A power added efficiency of a final stage power FET is estimated at 36%. An outline of 8.0X 6.2 X 1.9 $mm^3$ is comparable with MMICs'.

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